## Low Profile 0.3mm Pitch Connectors For FPC

### FH18 Series





### **Features**

### 1. Low profile 0.3mm pitch FPC connectors

In response to continuous miniturization of products, the demand for smaller contact spacing on connectors is increasing. Flexible printed circuits(FPC) with contact pitch of 0.3mm are used with increased frequency. FH18 series connectors fullfill this requirement. In addition, these connectors occupy less board space and are lighter than comparable connectors with contacts spaced at 0.5mm.

### 2. Improved Retention of FPC

Two types of contacts design are combined in the FH18 connector, zero insertion force(ZIF) and low insertion force(LIF). Inserted FPC is held in place by the LIF contact, allowing operator to close down the actuator and engage the ZIF contacts to assure complete connection.

### 3. Easy to use Flip-Lock

Flip-lock (rotating type) ZIF mechanism enables good connectivity of FPC by a simple operation and light force. No board space is required for flip lock operation as compared to slide lock ZIF connectors.

### 4. Placement on Board

The leads are on two sides of the connector, spaced on 0.6mm and are visible for solder joint inspection. Flat top surface of the connector allows board placement with automated equipment.

### 5. Variety of Contact Positions

The connectors are available with 17,21,25,27,39,45 and 51 contacts.

### Applications

Notebook computers, printers, PDAs, digital cameras and other compact devices for interconnecting the main circuit board with the LCD, PDP (Plasma Display),HDD or other device.





## Product Specifications

	Rating	Current rating 0.15A Voltage rating 30V AC	Operating temperature range Operating humidity range	-40℃ to +85℃ (Note 1) Relative humidity 90% max. (without condensation)	Storage temperature range Storage humidity range	-10°C to +50°C (Note 2) Relative humidity 90% max. (without condensation)
[	Applicable		Solder ploting (Note 4)			

 Applicable FPC
 t=0.2±0.03
 Solder plating (Note 4)

Item	Specification	Conditions
1.Insulation resistance	50M ohms minimum	100V DC
2.Withstanding voltage	No flashover or insulation breakdown.	90V AC/1 minute
3.Contact resistance	100m ohms maximum	1mA
4.Durability (Insertion/withdrawal)	Contact resistance : 100m ohms maximum No damage, cracks, or parts dislocation.	10 cycles
5.Vibration	No electrical discontinuity of $1\mu$ s or more Contact resistance: 100m ohms maximum No damage, cracks, or parts dislocation.	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 2 hours in each of the 3 directions.
6.Shock	No electrical discontinuity of $1\mu$ s or more Contact resistance: 100m ohms maximum No damage, cracks, or parts dislocation.	Acceleration of 490 m/s <sup>2</sup> , 11 ms duration, sine half-wave waveform, 3 cycles in each of the 3 axis.
7.Humidity (Steady state)	Contact resistance: 100m ohms maximum Insulation resistance: 50M ohms maximum No damage, cracks, or parts dislocation.	96 hours at temperature of $40^\circ C$ and humidity of 90% to 95%
8.Temperature cycle	Contact resistance: 100m ohms maximum. Insulation resistance: 50M ohms maximum. No damage, cracks, or parts dislocation.	5 cycles under conditions as follows; Temperature: $-40^{\circ}C \rightarrow 15 \text{ to } 35^{\circ}C \rightarrow 85^{\circ}C \rightarrow 15 \text{ to } 35^{\circ}C$ , Time: $30 \rightarrow 5\text{max}$ . $\rightarrow 30 \rightarrow 5 \text{ max}$ .(minutes)
9.Resistance to soldering heat	No deformation of components affecting performance.	Reflow: At the recommended temperature profile Manual soldering: 350±5°C for 3 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating Temperature Range and Humidity range covers nonconducting condition of installed connectors in storage, shipment or during transportation.

### Material

Part	Material	Finish	Remarks	
Insulator	LCP	Color : Beige		
insulator	LOF	Color : Black	UL 94V-0	
Contact	Phosphor bronze	Solder plating		
Metal fitting	Bronze	Solder plating		

## Ordering Information



1	Series name	FH18
2	Number of contacts	17, 21, 25, 27, 39, 45, 51
3	Contact pitch	0.3mm
4	Contact style	SHW : SMT horizontal mounting type
6	Plating specifications	No symbol : Solder plating
		(05) : Gold plating

## Connector Operating instruction

# **Operating Instruction** 1. FPC (Flat Printed Circuit) Insertion 0 A. Lift up carefully the lever to 90° max. angle. Do not forcefully exceed the 90° angle, as this may cause damage to connectoror the solder joints. B. Insert the FPC in the slot. 0 Assure that it is fully and straight inserted, with conductive surface facing down. Slight friction of the LIF contacts will be felt and the FPC will remain inserted. FPC conductor surface C. Push the lever down to a fully closed position. 8 2. FPC removal 0 A. Lift the lever up to a 90° angle. B. Slide out the FPC untill completely free.





Notes 1 Indicates the distance from J surface.

- The coplanarity of each lead and metal fitting within 0.1.(coplanarity : The distance between the lowest and highest land)
   This connector uses LIF(Low Insertion Force) and ZIF(Zero Insertion Force)
- contact design. Slight friction will be felt during insertion of FPC in the slot. Full insertion of FPC is required for secure connection.

							Unit: mm
Part Number	CL No.	Number of contacts	А	В	С	D	E
FH18-17S-0.3SHW	586-0684-5	17	7.6	4.2	4.8	6.15	5.4
FH18-21S-0.3SHW	586-0669-1	21	8.8	5.4	6.0	7.35	6.6
FH18-25S-0.3SHW	586-0685-8	25	10.0	6.6	7.2	8.55	7.8
FH18-27S-0.3SHW	586-0658-5	27	10.6	7.2	7.8	9.15	8.4
FH18-39S-0.3SHW	586-0646-6	39	14.2	10.8	11.4	12.75	12.0
FH18-45S-0.3SHW	586-0694-9	45	16.0	12.6	13.2	14.55	13.8
FH18-51S-0.3SHW	586-0671-3	51	17.8	14.4	15.0	16.35	15.6

Note : Packaging will be embossed tape and reel (2,500 pcs/reel) Please order by integral multiple of 2,500.

## Recommended Land/ Metal Mask Dimensions



\*Recommended metal mask thickness: t=0.15

### Recommended FPC Dimensions



Note 1 Polyimide and thermal hardening glue are a recommendation for the stiffener.

 $\boxed{2}$  When drawing a plated lead, 0.3 +0.04 -0.03 is also permitted.

					Unit: mm
Part Number	CL No.	Number of contacts	В	С	Е
FH18-17S-0.3SHW	586-0684-5	17	4.2	4.8	5.4
FH18-21S-0.3SHW	586-0669-1	21	5.4	6.0	6.6
FH18-25S-0.3SHW	586-0685-8	25	6.6	7.2	7.8
FH18-27S-0.3SHW	586-0658-5	27	7.2	7.8	8.4
FH18-39S-0.3SHW	586-0646-6	39	10.8	11.4	12.0
FH18-45S-0.3SHW	586-0694-9	45	12.6	13.2	13.8
FH18-51S-0.3SHW	586-0671-3	51	14.4	15.0	15.6



## Packaging Specifications

### •Embossed Carrier Tape Dimensions



								Unit: mm
Part Number	CL No.	Number of contacts	К	L	М	N	Q	R
FH18-17S-0.3SHW	586-0684-5	17	16	7.5	7.9	6.6	5.1	16.5
FH18-21S-0.3SHW	586-0669-1	21	16	7.5	9.1	7.8	6.3	16.5
FH18-25S-0.3SHW	586-0685-8	25	24	11.5	10.3	9.0	7.5	24.5
FH18-27S-0.3SHW	586-0658-5	27	24	11.5	10.9	9.6	8.1	24.5
FH18-39S-0.3SHW	586-0646-6	39	24	11.5	14.5	13.2	11.7	24.5
FH18-45S-0.3SHW	586-0694-9	45	24	11.5	16.3	15.0	13.5	24.5
FH18-51S-0.3SHW	586-0671-3	51	24	11.5	18.1	16.8	15.3	24.5

Note:One reel contains 2,500 connectors.

### Reel Dimensions





## Recommended Temperature Profile



Applicable Conditions

Reflow method	:	IR reflow		
Solder	:	Paste type 63Sn/37Pb		
		(Flux compor	ent of 11wt%)	
Test board	:	Glass epoxy	70 x 70 x 1.6mm	
Metal mask thickness	:	0.15mm		

Recommended temperature profile. The temperature may be slightly changed according to the solder paste type and amount.

## ● FH18 Series Construction (Recommended Specifications)

## 1. Single-Sided FPC

	Material Name	Material	Thickness (µm)
	Covering layer film	Polyamide 1 mil	25
	- Cover adhesive		25
▲	Surface treatment	Solder plating	5
► \(\)\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	Copper foil	Cu 1oz	35
◀	Base adhesive		25
✓	Base film	Polyamide 1 mil	25
	Reinforcement material adhesive		30
	Stiffener	Polyamide 3 mil	75
		Total	195

## 2. Using Double-Sided FPC

	Material Name	Mat	erial	Thickness (µm)
	- Covering layer film	Polyamide	1 mil	25
/</td <td>-Cover adhesive</td> <td></td> <td></td> <td>25</td>	-Cover adhesive			25
	Surface treatment	Solder plat	ing	5
	Through hole copper	Cu		15
►	Copper foil	Cu	1/2oz	18
	Base adhesive			18
	Base film	Polyamide	1 mil	25
	Base adhesive			18
	- Copper foil	Cu	1/2oz	18
	Cover adhesive			25
<i>\                                    </i>	Cover layer film	Polyamide	1 mil	25
	Reinforcement material adhesive			25
	Stiffener	Polyamide	1 mil	25
		Total		199

6976/8415

Note: Stiffener is not required for the double-sided FPC.

To prevent release of the lock due to FPC bending, please do not use copper foil on the rear side.

## 3. Precautions

- 1. This specification is a recommendation for the construction of the FH18 Series FPC (t=0.2  $\pm$ 0.03).
- 2. For details about the construction, please contact the FPC/FFC manufacturers.

## FPC/FFC Manufactures' Contact List

Sumitomo Bakelite Co., Ltd. Flexible Printed Circuit Board Division	TEL:+81 3 5462 4191
5-8, Higashi-shinagawa 2-chome, Shinagawa-ku, Tokyo, Japan	FAX:+81 3 5462 4882
Fujikura Ltd. Electronics Global Marketing Department	TEL:+81 3 5606 1165
1-5-1, Kiba, Koto-ku, Tokyo, Japan	FAX:+81 3 5606 1530
NOK Corporation Sales Division Overseas Business Department 1-12-15, Shiba-Daimon, Minato-ku, Tokyo, Japan	TEL:+81 3 3432 6976/ FAX:+81 3 3432 3919